

## N - CHANNEL ENHANCEMENT MODE FAST POWER MOS TRANSISTOR

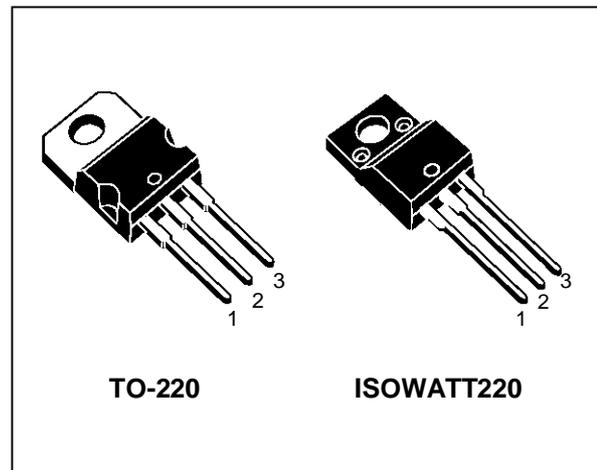
PRELIMINARY DATA

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STP3NA90	900 V	< 5.3 Ω	3 A
STP3NA90FI	900 V	< 5.3 Ω	1.9 A

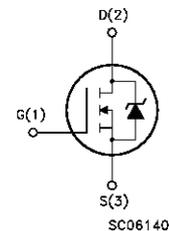
- TYPICAL R<sub>DS(on)</sub> = 4.4 Ω
- ± 30V GATE TO SOURCE VOLTAGE RATING
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW INTRINSIC CAPACITANCES
- GATE CHARGE MINIMIZED
- REDUCED THRESHOLD VOLTAGE SPREAD

### APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVE



### INTERNAL SCHEMATIC DIAGRAM



### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP3NA90	STP3NA90FI	
V <sub>DS</sub>	Drain-Source Voltage (V <sub>GS</sub> = 0)	900		V
V <sub>DGR</sub>	Drain-Gate Voltage (R <sub>GS</sub> = 20 KΩ)	900		V
V <sub>GS</sub>	Gate-Source Voltage	± 30		V
I <sub>D</sub>	Drain-Current (continuous) at T <sub>c</sub> = 25°C	3	1.9	A
I <sub>D</sub>	Drain-Current (continuous) at T <sub>c</sub> = 100°C	2	1.2	A
I <sub>DM</sub> (•)	Drain-Current (Pulsed)	12	12	A
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25°C	100	40	W
	Derating Factor	1.25	0.32	W/°C
V <sub>ISO</sub>	Insulation Withstand Voltage (DC)	-	2000	V
T <sub>stg</sub>	Storage Temperature	-65 to 150		°C
T <sub>j</sub>	Max Operating Junction Temperature	150		°C

(•)Pulse width limited by safe operating area

# STP3NA90/FI

## THERMAL DATA

			TO220	ISOWATT220	
R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	0.8	3.12	°C/W
R <sub>thj-amb</sub>	Thermal Resistance Junction-ambient	Max	62.5		°C/W
R <sub>thc-sink</sub>	Thermal Resistance Case-sink	Typ	0.5		°C/W
T <sub>l</sub>	Maximum Lead Temperature For Soldering Purpose		300		°C

## AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max, δ < 1%)	3	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting T <sub>j</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	45	mJ
E <sub>AR</sub>	Repetitive Avalanche Energy (pulse width limited by T <sub>j</sub> max, δ < 1%)	2	mJ
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (T <sub>c</sub> = 100 °C, pulse width limited by T <sub>j</sub> max, δ < 1%)	2	A

## ELECTRICAL CHARACTERISTICS (T<sub>case</sub> = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA V <sub>GS</sub> = 0	900			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating x 0.8 T <sub>c</sub> = 125 °C			250 1000	μA μA
I <sub>GSS</sub>	Gate-Source Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 30 V			±100	mA

ON (\*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 250 μA	2.25	3	3.75	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	V <sub>GS</sub> = 10 V I <sub>D</sub> = 1.5 A V <sub>GS</sub> = 10 V I <sub>D</sub> = 1.5 A T <sub>c</sub> = 100 °C		4.4	5.3 10.6	Ω Ω
I <sub>D(on)</sub>	On State Drain Current	V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DS(on)max</sub> V <sub>GS</sub> = 10 V	3			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	V <sub>DS</sub> > I <sub>D(on)</sub> x R <sub>DS(on)max</sub> I <sub>D</sub> = 1.5 A	1.5	2.8		S
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25 V f = 1 MHz V <sub>GS</sub> = 0		690	900	pF
C <sub>oss</sub>	Output Capacitance			80	105	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			20	30	pF

**ELECTRICAL CHARACTERISTICS** (continued)

## SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Time	$V_{DD} = 450\text{ V}$		10	15	ns
$t_r$	Rise Time	$I_D = 1.5\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$		10	15	ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 720\text{ V}$ $I_D = 3\text{ A}$ $R_G = 47\ \Omega$ $V_{GS} = 10\text{ V}$		360		A/ $\mu$ s
$Q_g$	Total Gate Charge	$V_{DD} = 720\text{ V}$ $I_D = 3\text{ A}$ $V_{GS} = 10\text{ V}$		35	50	nC
$Q_{gs}$	Gate-Source Charge			6		nC
$Q_{gd}$	Gate-Drain Charge			14		nC

## SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(Voff)}$	Off-voltage Rise Time	$V_{DD} = 720\text{ V}$ $I_D = 3\text{ A}$		11	10	ns
$t_f$	Fall Time	$R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$		8	13	ns
$t_c$	Cross-over Time			19	26	ns

## SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain Current				3	A
$I_{SDM}(\bullet)$	Source-drain Current (pulsed)				12	A
$V_{SD} (*)$	Forward On Voltage	$I_{SD} = 3\text{ A}$ $V_{GS} = 0$			1.6	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = 3\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 100\text{ V}$ $T_j = 150\text{ }^\circ\text{C}$		950		ns
$Q_{rr}$	Reverse Recovery Charge			14.2		$\mu$ C
$I_{RRM}$	Reverse Recovery Current			30		A

(\*) Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area